

DHG100X1200NA

preliminary

 $V_{RRM} = 1200 V$

 $I_{FAV} = 2x \quad 50 A$

 t_{rr} = 200 ns

High Performance Fast Recovery Diode Low Loss and Soft Recovery Parallel legs

Sonic Fast Recovery Diode

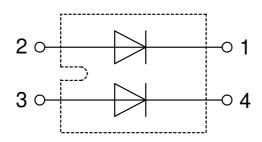
Part number

DHG100X1200NA



Backside: Isolated





Features / Advantages:

- Planar passivated chips
- Very low leakage current
 Vary about reasons times
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

Disclaimer Notice

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.



DHG100X1200NA

preliminary

Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blockii	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking vo	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
IR	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			100	μΑ
		$V_R = 1200 V$	$T_{VJ} = 125^{\circ}C$			1.2	mΑ
V _F	forward voltage drop	I _F = 50 A	$T_{VJ} = 25^{\circ}C$			2.16	V
		$I_F = 100 \text{ A}$				2.78	٧
		$I_F = 50 \text{ A}$	T _{VJ} = 125°C			2.13	٧
		$I_F = 100 \text{ A}$				2.97	٧
I FAV	average forward current	$T_C = 65^{\circ}C$	T _{VJ} = 150°C			50	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		$T_{VJ} = 150$ °C			1.26	٧
\mathbf{r}_{F}	slope resistance	ss calculation only				15.3	mΩ
R _{thJC}	thermal resistance junction to case)				0.6	K/W
R _{thCH}	thermal resistance case to heatsin	k			0.1		K/W
P _{tot}	total power dissipation		$T_C = 25^{\circ}C$			200	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			500	Α
CJ	junction capacitance	$V_R = 600 \text{V} f = 1 \text{MHz}$	$T_{VJ} = 25^{\circ}C$		27		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 ^{\circ}\text{C}$		45		Α
		$I_F = 60 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125$ °C		60		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 60 \text{ A}; V_R = 600 \text{ V} \\ -di_F /dt = 1200 \text{ A}/\mu\text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}\text{C}$		200		ns
	J		$T_{VJ} = 125^{\circ}C$		350		ns



DHG100X1200NA

preliminary

Package SOT-227B (minibloc)			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal					100	Α
T _{VJ}	virtual junction temperature	9			-40		150	°C
Top	operation temperature				-40		125	°C
T _{stg}	storage temperature				-40		150	°C
Weight						30		g
M _D	mounting torque				1.1		1.5	Nm
$\mathbf{M}_{_{T}}$	terminal torque				1.1		1.5	Nm
d _{Spp/App}	oroonago distanco on surf	and Letriking distance through air	terminal to terminal	10.5	3.2			mm
$d_{Spb/Apb}$	creepage distance on surface striking distance through air		terminal to backside	8.6	6.8			mm
V _{ISOL}	isolation voltage				3000			V
		t = 1 minute	50/60 Hz, RMS; IsoL ≤ 1 mA		2500			V

Product Marking Location Lot#

Part description

D = Diode H = Sonic Fast Recovery Diode

G = extreme fast

100 = Current Rating [A]

X = Parallel legs 1200 = Reverse Voltage [V]

NA = SOT-227B (minibloc)

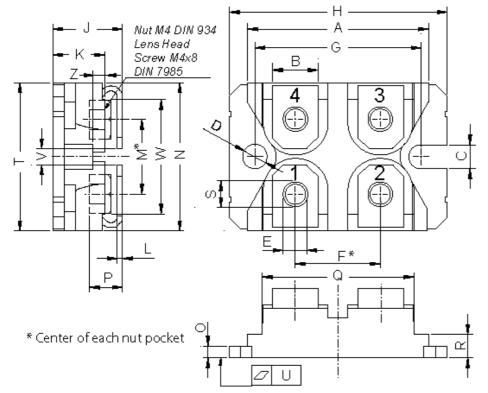
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DHG100X1200NA	DHG100X1200NA	Tube	10	507759

Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 150^{\circ}C$
$I - V_0$)— <u>R</u> o	Fast Diode		
V _{0 max}	threshold voltage	1.26		V
R _{0 max}	slope resistance *			mΩ

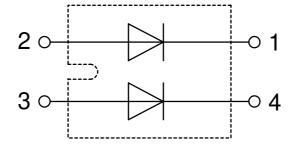


preliminary

Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	31.50	31.88	1.240	1.255	
В	7.80	8.20	0.307	0.323	
С	4.09	4.29	0.161	0.169	
D	4.09	4.29	0.161	0.169	
Е	4.09	4.29	0.161	0.169	
F	14.91	15.11	0.587	0.595	
G	30.12	30.30	1.186	1.193	
Н	37.80	38.23	1.488	1.505	
J	11.68	12.22	0.460	0.481	
K	8.92	9.60	0.351	0.378	
L	0.74	0.84	0.029	0.033	
M	12.50	13.10	0.492	0.516	
N	25.15	25.42	0.990	1.001	
0	1.95	2.13	0.077	0.084	
Р	4.95	6.20	0.195	0.244	
Q	26.54	26.90	1.045	1.059	
R	3.94	4.42	0.155	0.167	
S	4.55	4.85	0.179	0.191	
Т	24.59	25.25	0.968	0.994	
U	-0.05	0.10	-0.002	0.004	
V	3.20	5.50	0.126	0.217	
W	19.81	21.08	0.780	0.830	
Ζ	2.50	2.70	0.098	0.106	





Fast Diode

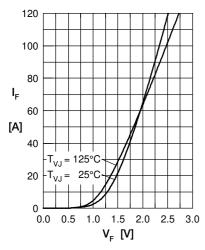


Fig. 1 Typ. Forward current versus V_F

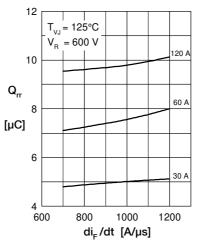


Fig. 2 Typ. reverse recov. charge Q_{rr} versus di/dt

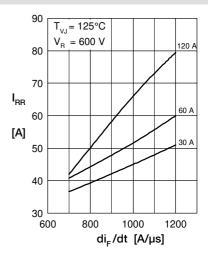


Fig. 3 Typ. peak reverse current I_{RM} versus di/dt

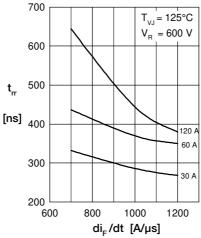


Fig. 4 Dynamic parameters \mathbf{Q}_{rr} , \mathbf{I}_{RM} versus \mathbf{T}_{VJ}

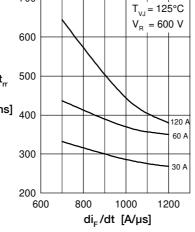


Fig. 5 Typ. recovery time t_{rr} versus di/dt

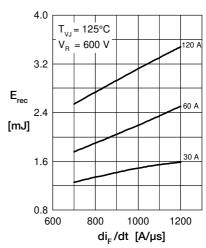


Fig. 6 Typ. recovery energy E_{rec} versus di/dt

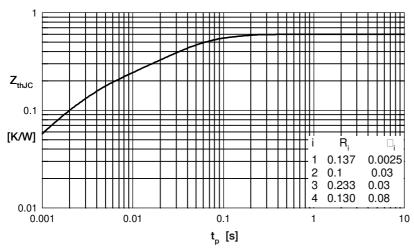


Fig. 7 Typ. transient thermal impedance junction to case